

Embedded Active Components and Integrated Passives: *Technologies & Markets*

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The introduction of embedded active components and integrated passives may be the most significant development in the electronics industry since the introduction of microvia technology. What applications are driving demand? Which companies are using the technologies? Is the infrastructure sufficiently developed? The new analysis from TechSearch International provides answers to these questions and more.

The report includes both embedded active and passive devices in IC packages, modules, and printed circuit boards. It details the differences between formed and placed components and provides insight into the drivers for the adoption of each technology. Trends in each of the segments are described including processes, roadmaps, material and equipment issues, thermal and electrical issues, test, reliability, applications, and market growth. Alternatives to embedding in laminate substrates are reviewed. Implementation of embedded actives and passives will impact the entire supply chain. The report can help you position your company to take advantage of new market opportunities.

Executive Summary

1 Introduction

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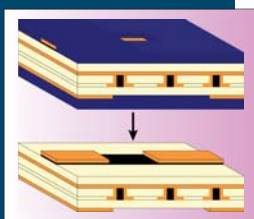
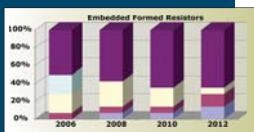
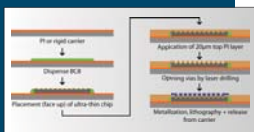
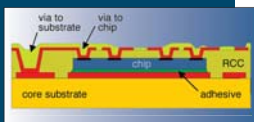
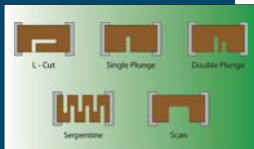
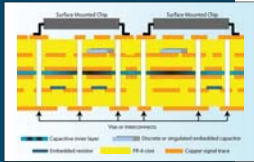
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